

# 4 LAYER MULTILAYER BOARD



## Production Sequence:-

- 1)     a) Photoplot outer and inner layer artworks as negatives  
       b) Photoplot Soldermask Artworks (Positives) and Ident Artworks (Negatives) if required.
- 2)     CNC Drill Two 3mm Tooling/ Registration holes in inner layer board blank
- 3)     Brush clean and dry inner layer blank
- 4)     Dry Film laminate inner layer blank
- 5)     Align inner layer artworks with tooling holes and tape each side to blank so they cannot move.
- 6)     Expose to U.V.
- 7)     Conveyorise Develop
- 8)     Conveyorise Etch
- 9)     Tank Strip Wash and Dry
- 10)    Build up multilayer set. Place between press plates and run Heating/Cooling Cycle.
- 11)    Remove from Press.
- 12)    Place Board Set back on CNC machine locating it on Tooling Pins and Drill all holes.
- 13)    Brush Clean
- 14)    Through Hole Plate
- 15)    Dry Film
- 16)    Expose outer layers
- 17)    Develop
- 18)    Etch
- 19)    Strip
- 20)    Clean
- 21)    Tin



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